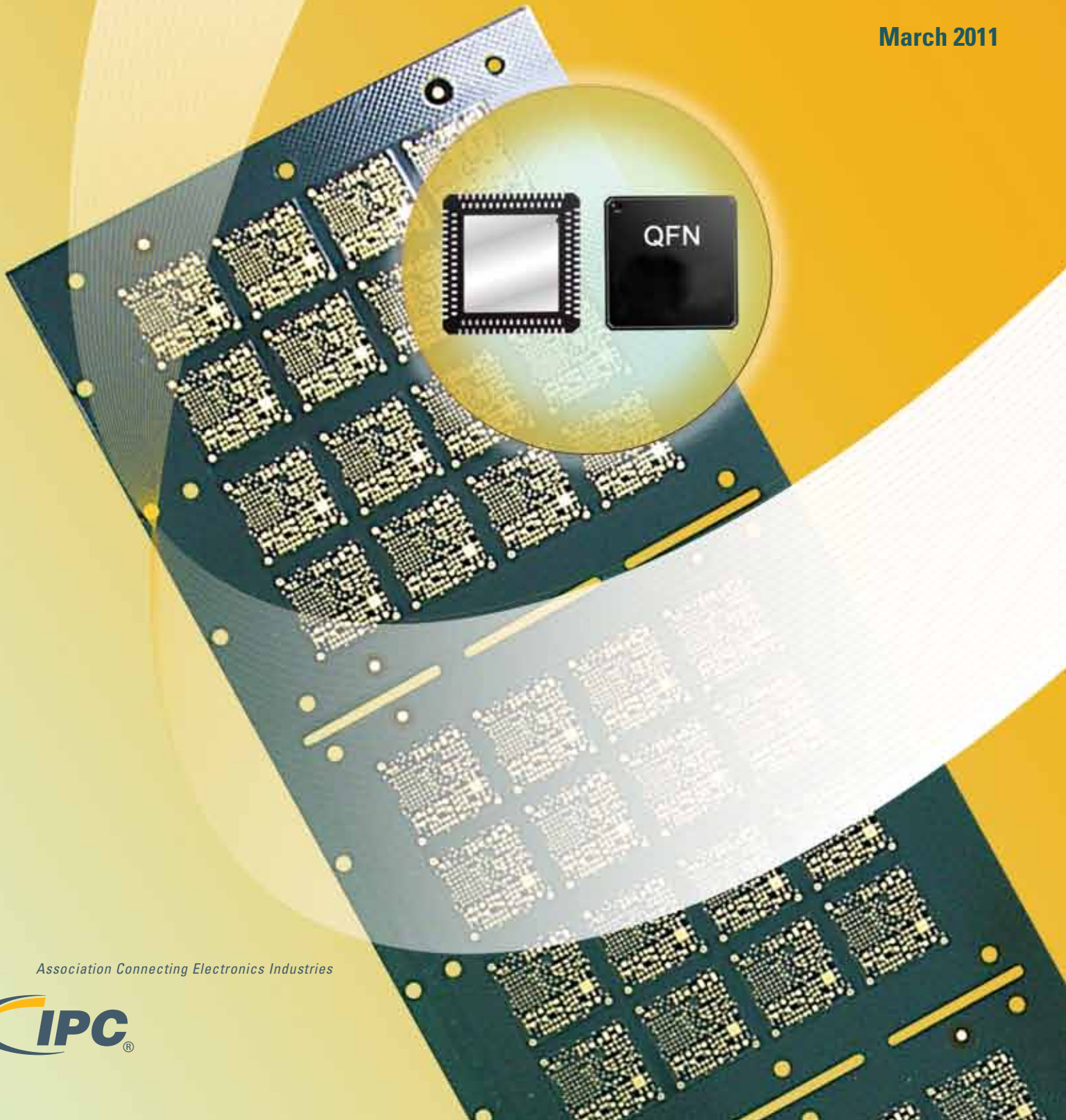


IPC-7093

Design and Assembly Process Implementation for Bottom Termination Components

March 2011



Association Connecting Electronics Industries



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Design and Assembly Process Implementation for Bottom Termination SMT Components

Developed by the IPC Bottom Termination Components (BTC) Task Group (5-21h) of the Assembly & Joining Processes Committee (5-20) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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